

N- AND P-CHANNEL ENHANCEMENT MODE POWER MOSFET

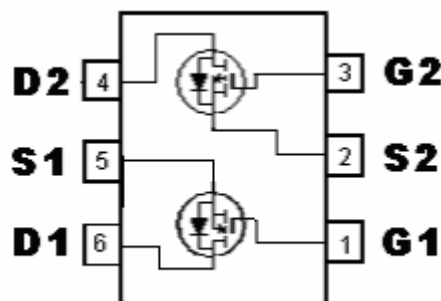
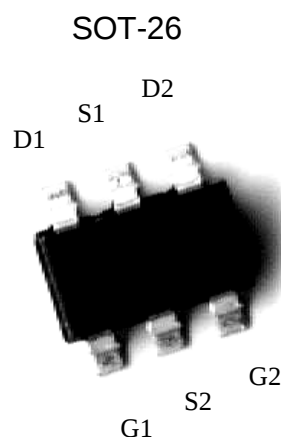
Features:

- Simple drive requirement
- Low gate charge
- Low on-resistance
- Fast switching speed
- Pb-free lead plating and halogen-free package

Description:

The KWC3585N6 consists of a N-channel and a P-channel enhancement-mode MOSFET in a single SOT-26 package, providing the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The SOT-26 package is universally preferred for all commercial-industrial surface mount applications.



G : Gate
 S : Source
 D : Drain

	N-CH	P-CH
BV _{DSS}	20V	-20V
I _D	4.5A (V _{GS} =4.5V)	-3A (V _{GS} =-4.5 V)
R _{DS(on)} (TYP.)	27mΩ (V _{GS} =4.5V)	78mΩ (V _{GS} =-4.5V)
	37mΩ (V _{GS} =2.5V)	115mΩ (V _{GS} =-2.5V)
	82mΩ (V _{GS} =1.5V)	280mΩ (V _{GS} =-1.5V)

Ordering Information

Device	Package	Shipping
KWC3585N6	SOT-26 (Pb-free lead plating and halogen-free package)	3000 pcs / Tape & Reel

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Limits		Unit
		N-channel	P-channel	
Drain-Source Breakdown Voltage	BV _{DSS}	20	-20	V
Gate-Source Voltage	V _{GS}	±12	±12	V
Continuous Drain Current @T _A =25 °C (Note 1)	I _D	4.5	-3	A
Continuous Drain Current @T _A =70 °C (Note 1)	I _D	3.6	-2.4	A
Pulsed Drain Current (Note 2)	I _{DM}	20	-20	A
Total Power Dissipation (Note 1)	P _d	1.14		W
Linear Derating Factor		0.01		W / °C
Operating Junction and Storage Temperature	T _j , T _{stg}	-55~+150		°C

Note : 1.Surface mounted on 1 in² copper pad of FR-4 board, t≤5 sec
2.Pulse width limited by maximum junction temperature

N-Channel Electrical Characteristics (Tj=25°C, unless otherwise specified)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV _{DSS}	20	-	-	V	V _{GS} =0, I _D =250μA
ΔBV _{DSS} /ΔT _j	-	0.02	-	V/°C	Reference to 25°C, I _D =1mA
V _{GS(th)}	0.5	0.7	1.2	V	V _{DS} =V _{GS} , I _D =250μA
I _{GSS}	-	-	±100	nA	V _{GS} =±12V, V _{DS} =0
I _{DSS}	-	-	1	μA	V _{DS} =20V, V _{GS} =0
	-	-	10		V _{DS} =16V, V _{GS} =0, T _j =70°C
*R _{DS(ON)}	-	27	40	mΩ	I _D =3.5A, V _{GS} =4.5V
	-	37	50		I _D =1.2A, V _{GS} =2.5V
	-	82	105		I _D =0.5A, V _{GS} =1.5V
*G _{FS}	-	7	-	S	V _{DS} =5V, I _D =3A
Dynamic					
C _{iss}	-	423	-	pF	V _{DS} =20V, V _{GS} =0, f=1MHz
C _{oss}	-	50	-		
C _{rss}	-	48	-		
*t _{d(ON)}	-	6	-	ns	V _{DS} =15V, I _D =1A, V _{GS} =5V, R _G =3.3Ω, R _D =15Ω
*t _r	-	8	-		
*t _{d(OFF)}	-	11	-		
*t _f	-	10	-		
*Q _g	-	6	-	nC	V _{DS} =16V, I _D =3A, V _{GS} =4.5V
*Q _{gs}	-	0.8	-		
*Q _{gd}	-	2.5	-		
Source-Drain Diode					
*V _{SD}	-	0.77	1.2	V	V _{GS} =0V, I _S =1.2A
*t _{rr}	-	16	-	ns	I _S =3A, V _{GS} =0V, dI/dt=100A/μs
*Q _{rr}	-	8	-	nC	

*Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%

P-Channel Electrical Characteristics (Tj=25°C, unless otherwise specified)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV _{DSS}	-20	-	-	V	V _{GS} =0, I _D =-250μA
ΔBV _{DSS} /ΔT _j	-	-0.01	-	V/°C	Reference to 25°C, I _D =-1mA
V _{GS(th)}	-	-0.8	-1.2	V	V _{DS} =V _{GS} , I _D =-250μA
I _{GSS}	-	-	±100	nA	V _{GS} =±12V, V _{DS} =0
I _{DSS}	-	-	-1	μA	V _{DS} =-20V, V _{GS} =0
	-	-	-25		V _{DS} =-16V, V _{GS} =0, T _j =70°C
*R _{DS(ON)}	-	78	105	mΩ	I _D =-2.5A, V _{GS} =-4.5V
	-	115	150		I _D =-2A, V _{GS} =-2.5V
	-	280	350		I _D =-0.5A, V _{GS} =-1.5V
*G _{FS}	-	5	-	S	V _{DS} =-5V, I _D =-2A
Dynamic					
C _{iss}	-	429	-	pF	V _{DS} =-20V, V _{GS} =0, f=1MHz
C _{oss}	-	45	-		
C _{rss}	-	41	-		
*t _{d(ON)}	-	6	-	ns	V _{DS} =-10V, I _D =-1A, V _{GS} =-10V, R _G =3.3Ω, R _D =10Ω
*t _r	-	17	-		
*t _{d(OFF)}	-	16	-		
*t _f	-	5	-		
*Q _g	-	6	-	nC	V _{DS} =-16V, I _D =-2A, V _{GS} =-4.5V
*Q _{gs}	-	0.8	-		
*Q _{gd}	-	2.4	-		
Source-Drain Diode					
*V _{SD}	-	-0.82	-1.2	V	V _{GS} =0V, I _S =-1.2A
*t _{rr}	-	20	-	ns	I _S =-2A, V _{GS} =0V, dI/dt=100A/μs
*Q _{rr}	-	15	-	nC	

*Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%

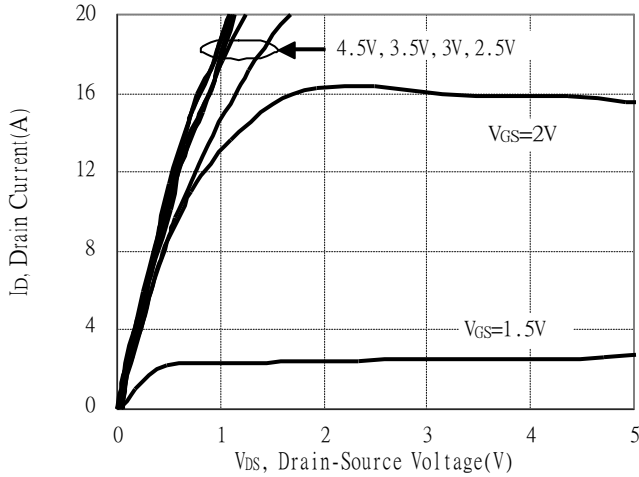
Thermal Data

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-case, max	R _{θJC}	80	°C/W
Thermal Resistance, Junction-to-ambient, max	R _{θJA}	110 (Note)	°C/W

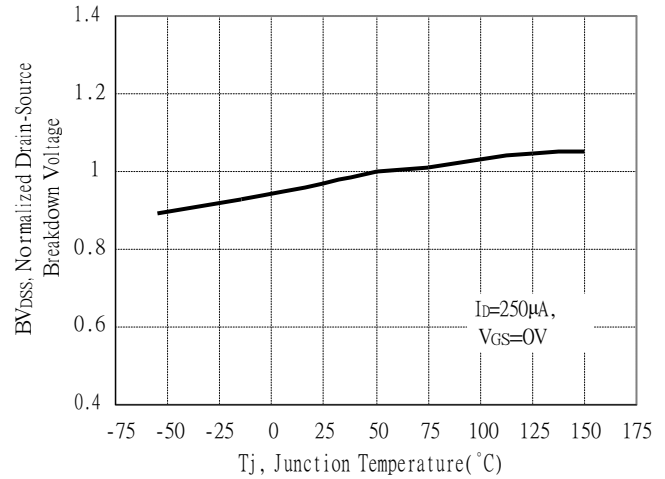
Note : Surface mounted on 1 in² copper pad of FR-4 board, t≤5 sec; 180°C/W when mounted on minimum copper pad

N-channel Typical Characteristics

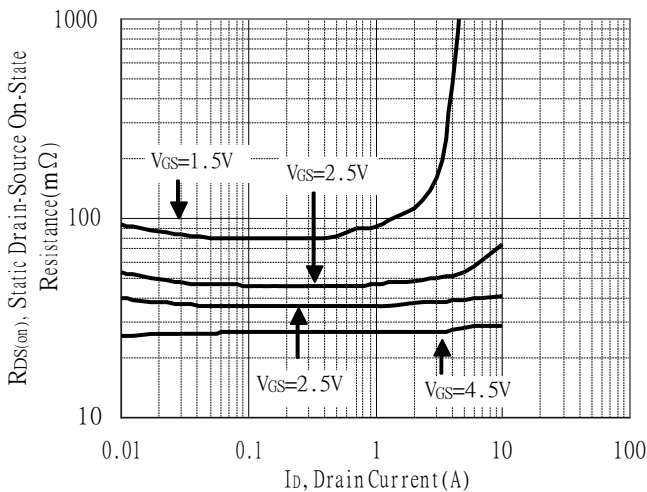
Typical Output Characteristics



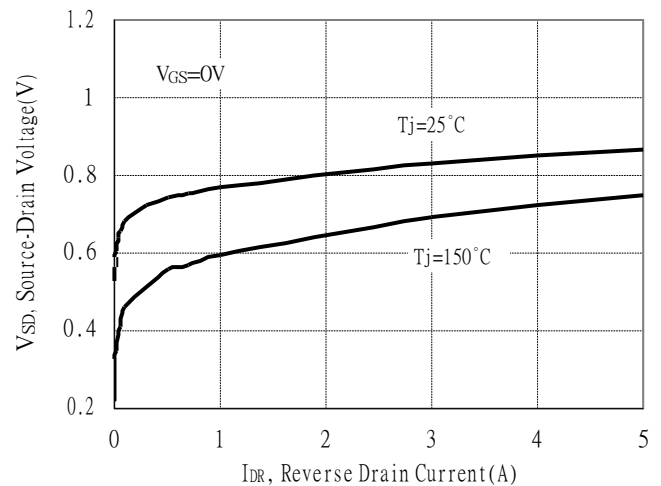
Breakdown Voltage vs Ambient Temperature



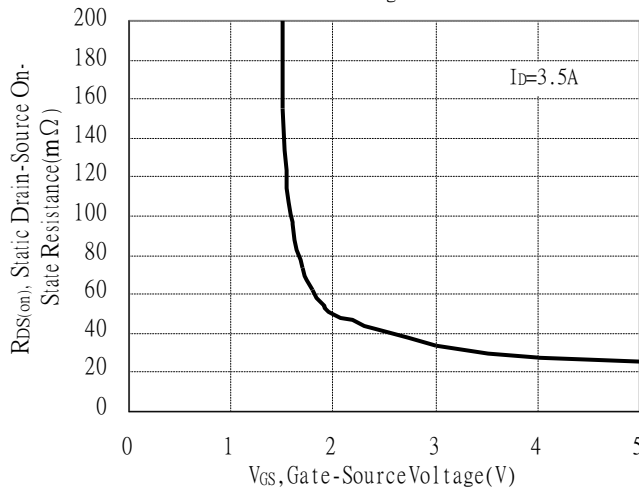
Static Drain-Source On-State resistance vs Drain Current



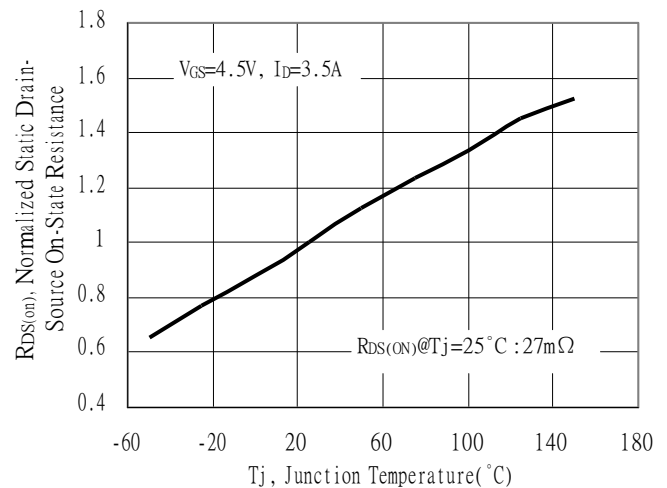
Reverse Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

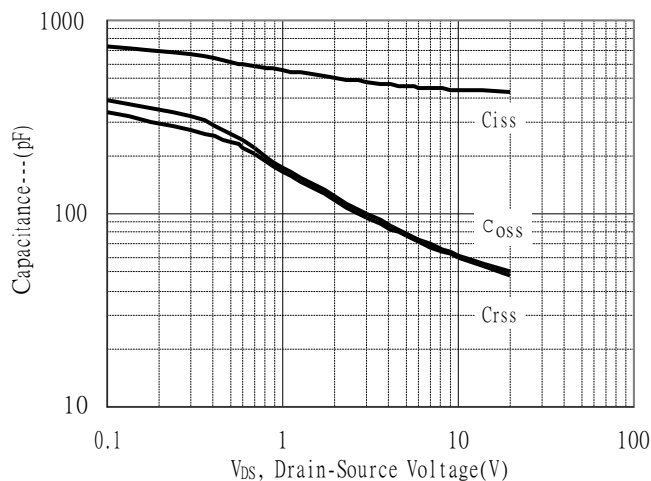


Drain-Source On-State Resistance vs Junction Temperature

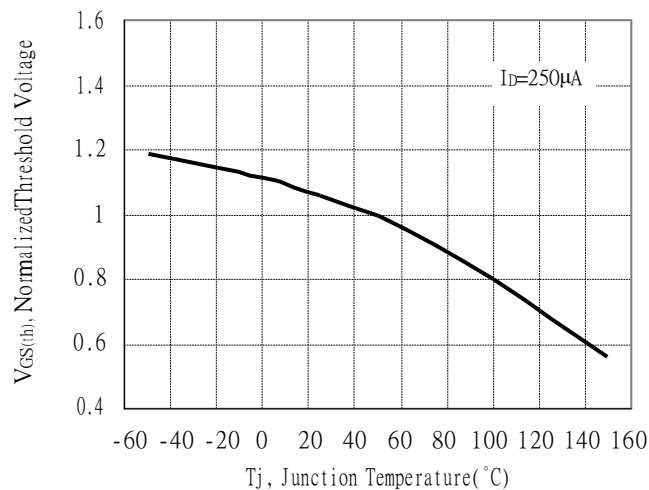


N-channel Typical Characteristics(Cont.)

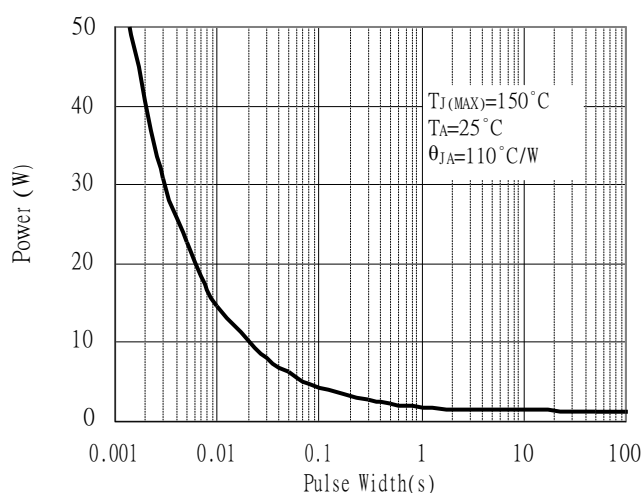
Capacitance vs Drain-to-Source Voltage



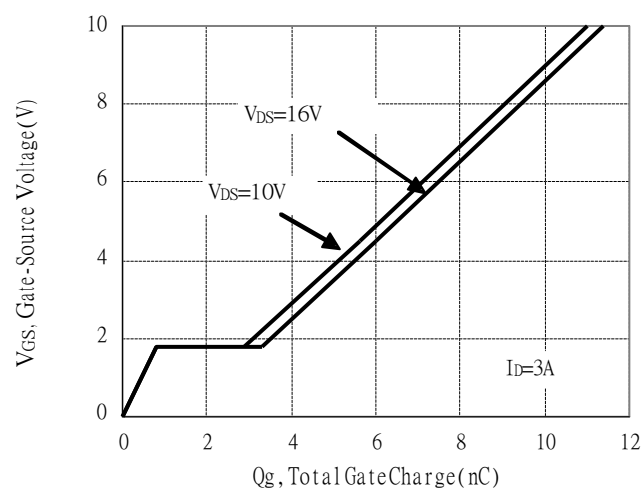
Threshold Voltage vs Junction Temperature



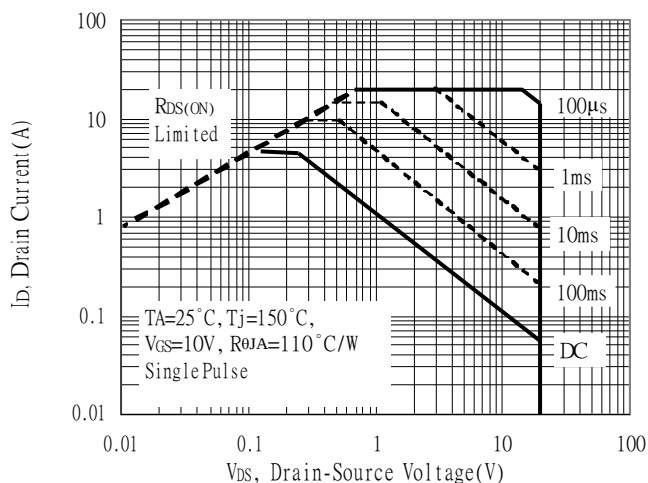
Single Pulse Power Rating, Junction to Ambient



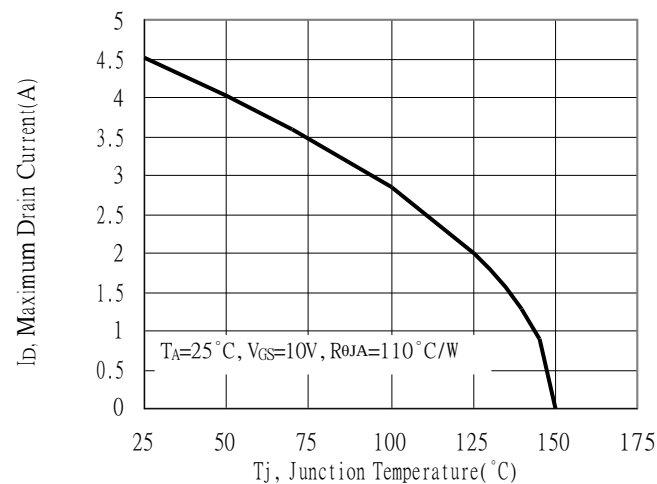
Gate Charge Characteristics



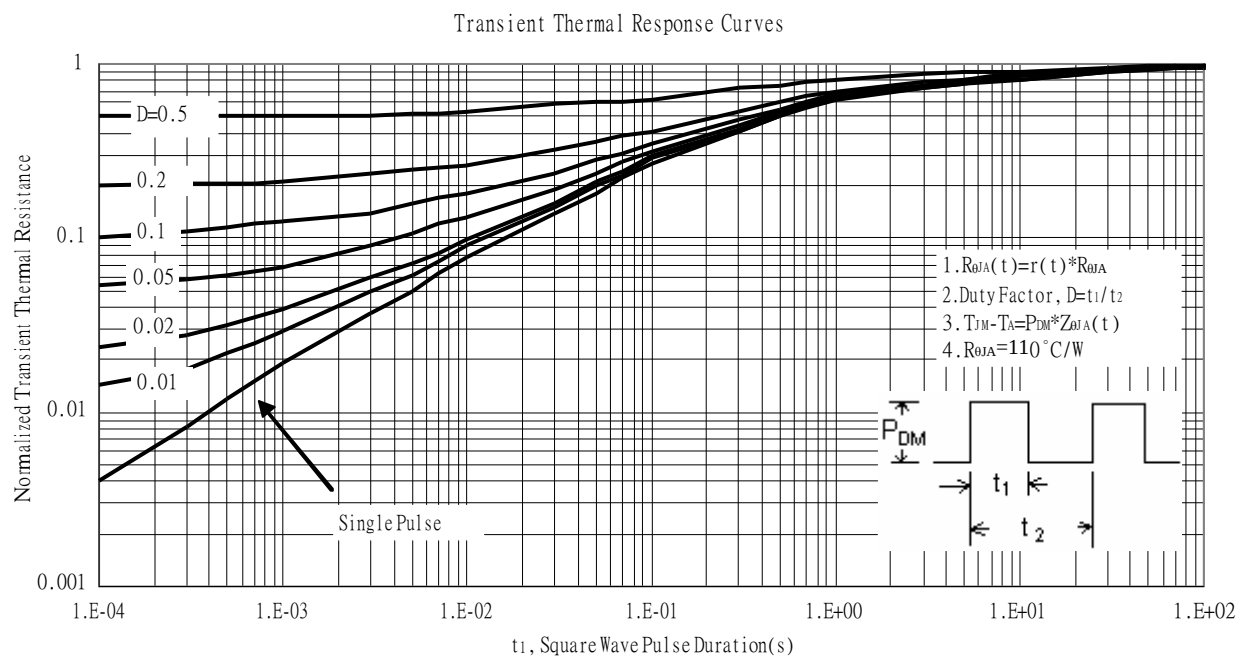
Maximum Safe Operating Area



Maximum Drain Current vs Junction Temperature

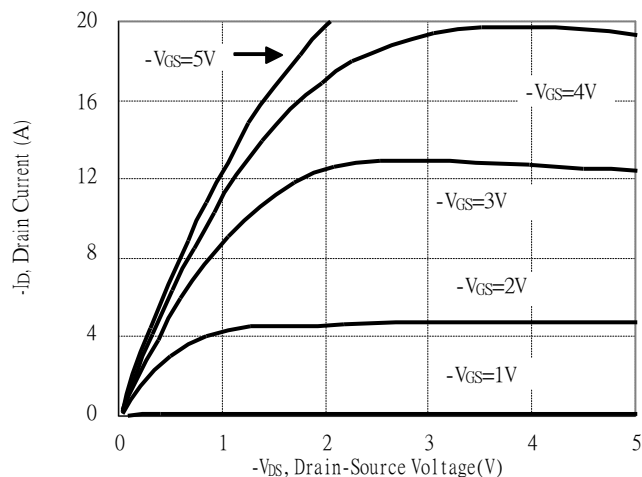


N-channel Typical Characteristics(Cont.)

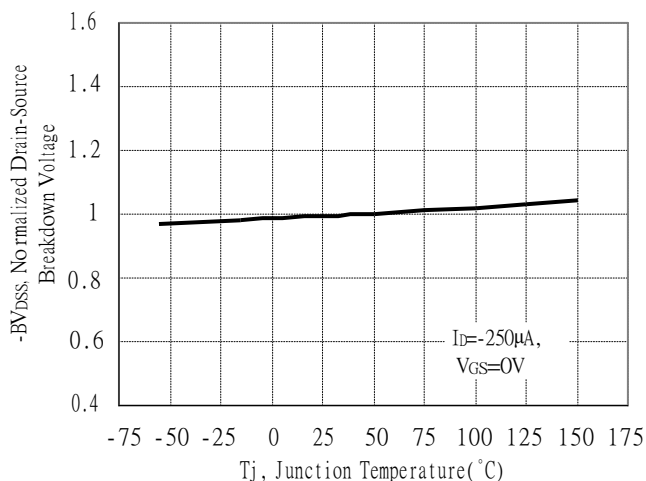


P-channel Typical Characteristics

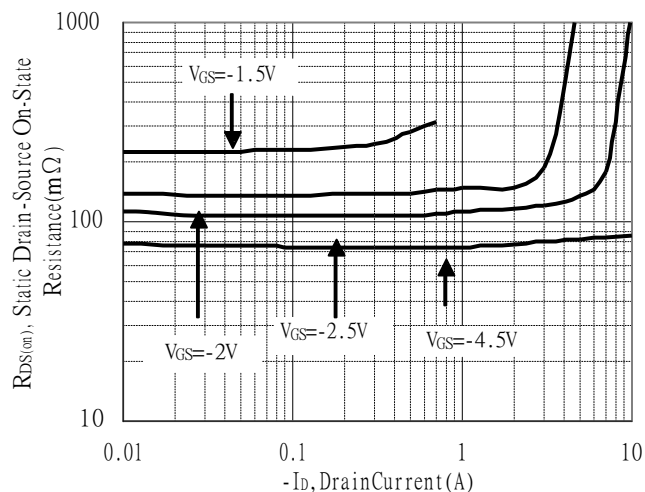
Typical Output Characteristics



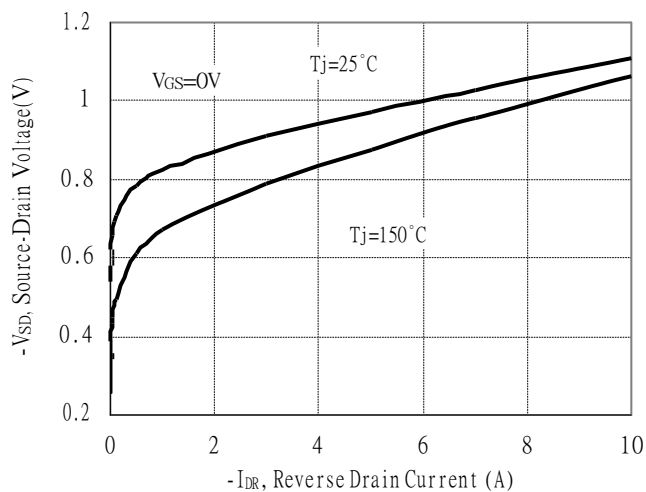
Breakdown Voltage vs Ambient Temperature



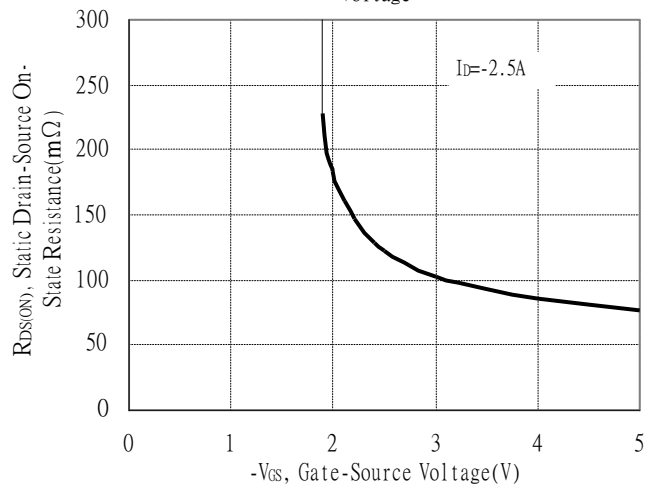
Static Drain-Source On-State resistance vs Drain Current



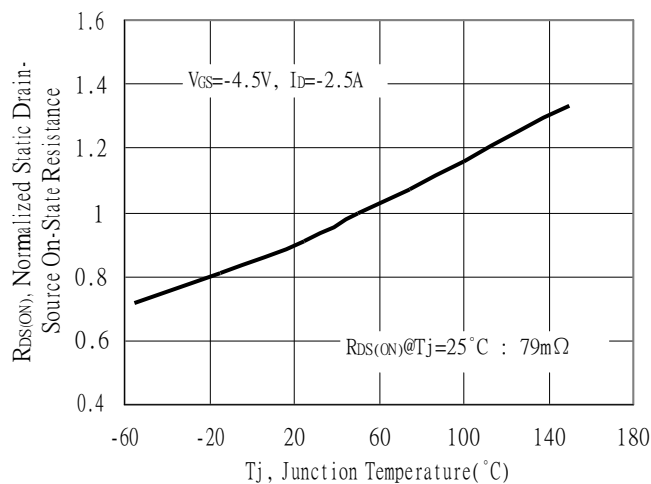
Reverse Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

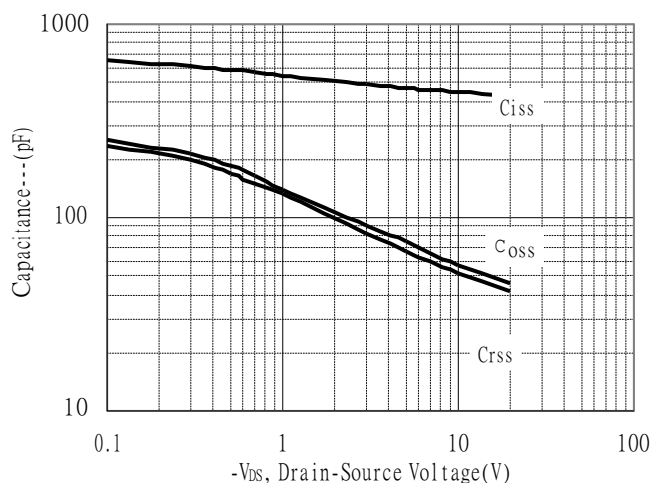


Drain-Source On-State Resistance vs Junction Temperature

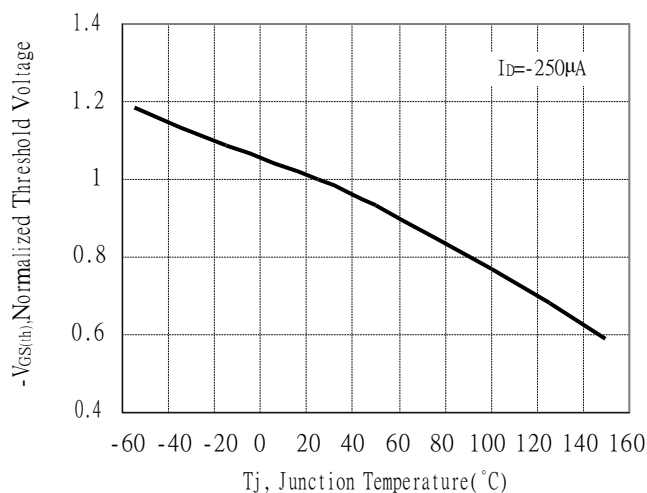


P-channel Typical Characteristics(Cont.)

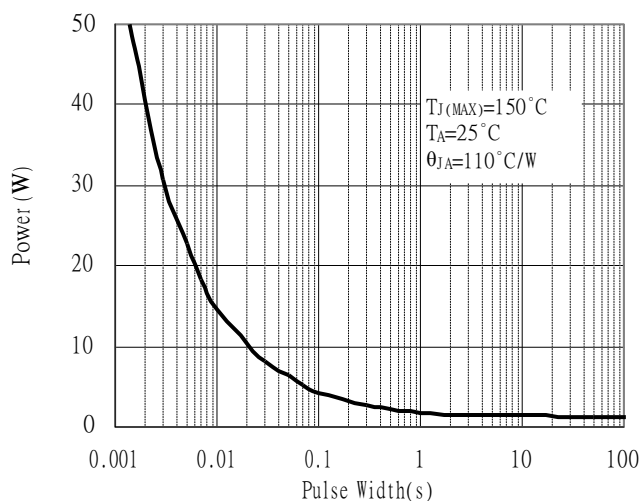
Capacitance vs Drain-to-Source Voltage



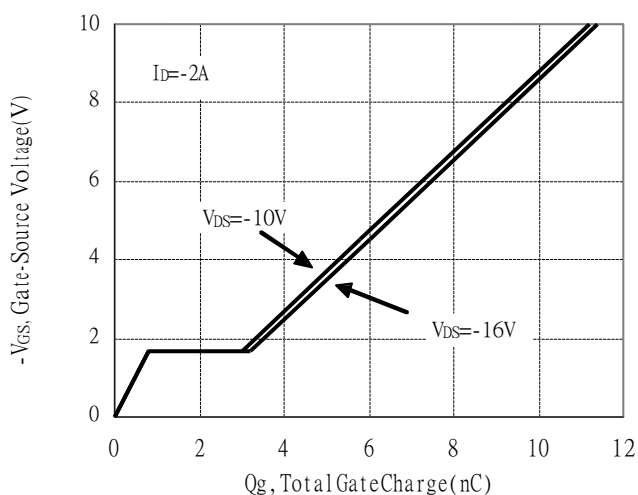
Threshold Voltage vs Junction Temperature



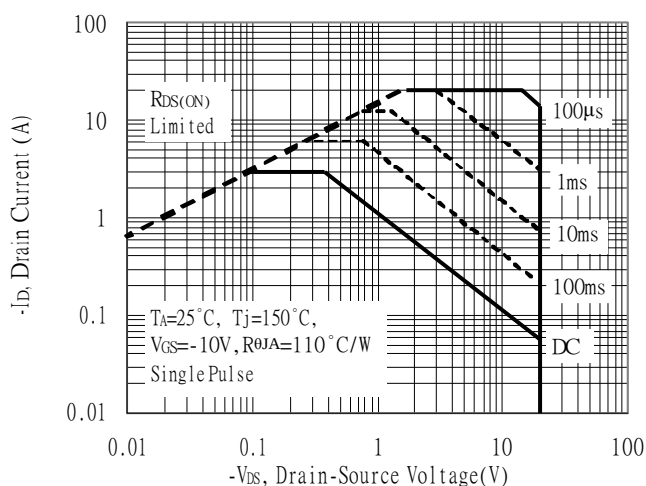
Single Pulse Power Rating, Junction to Ambient



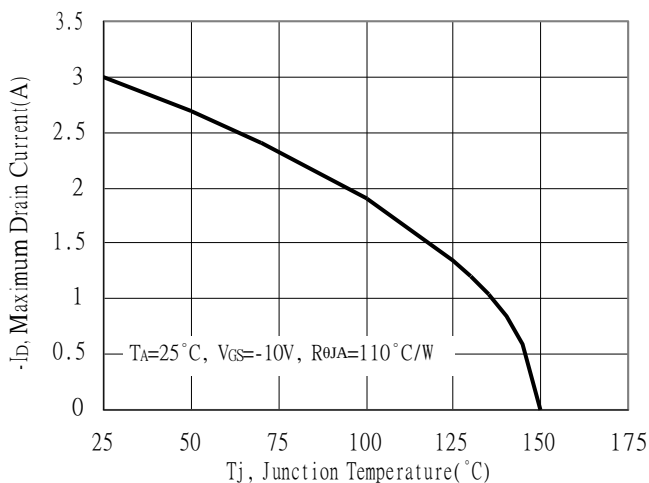
Gate Charge Characteristics



Maximum Safe Operating Area

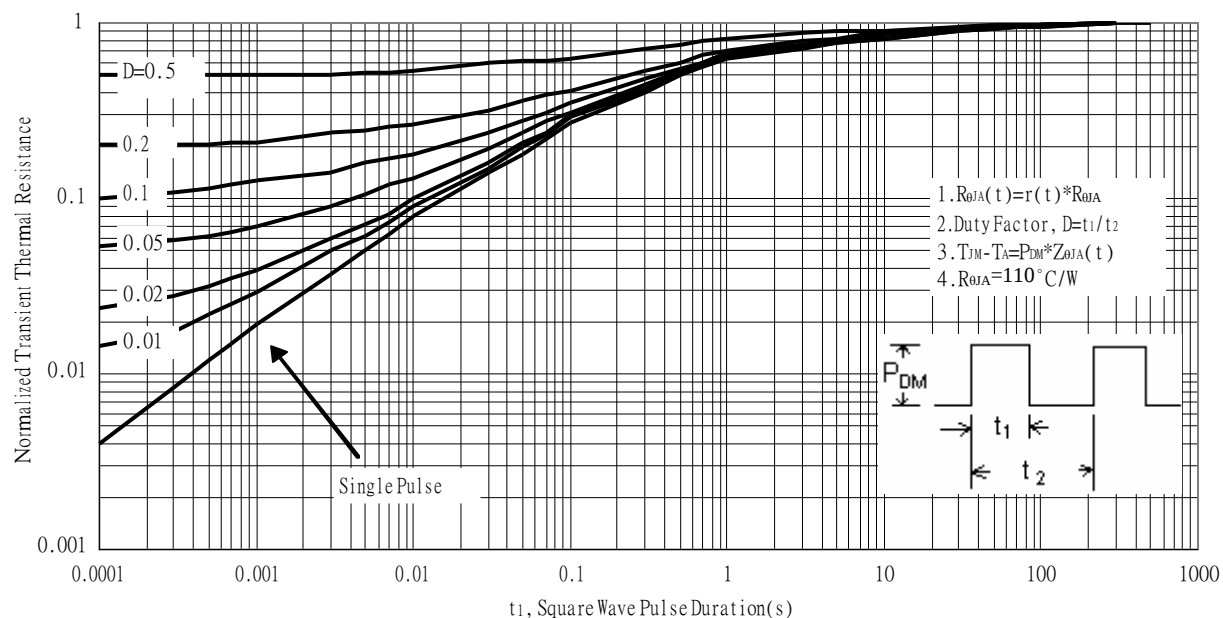


Maximum Drain Current vs Junction Temperature

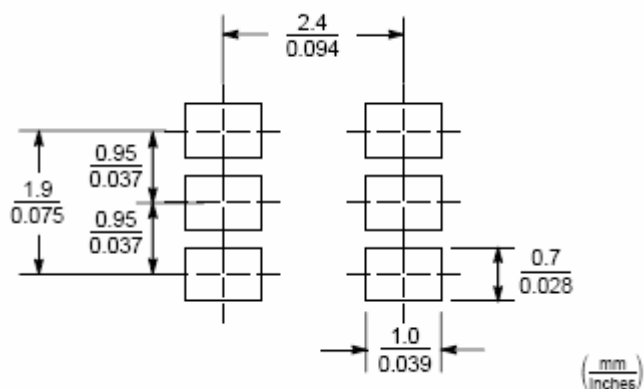


P-channel Typical Characteristics(Cont.)

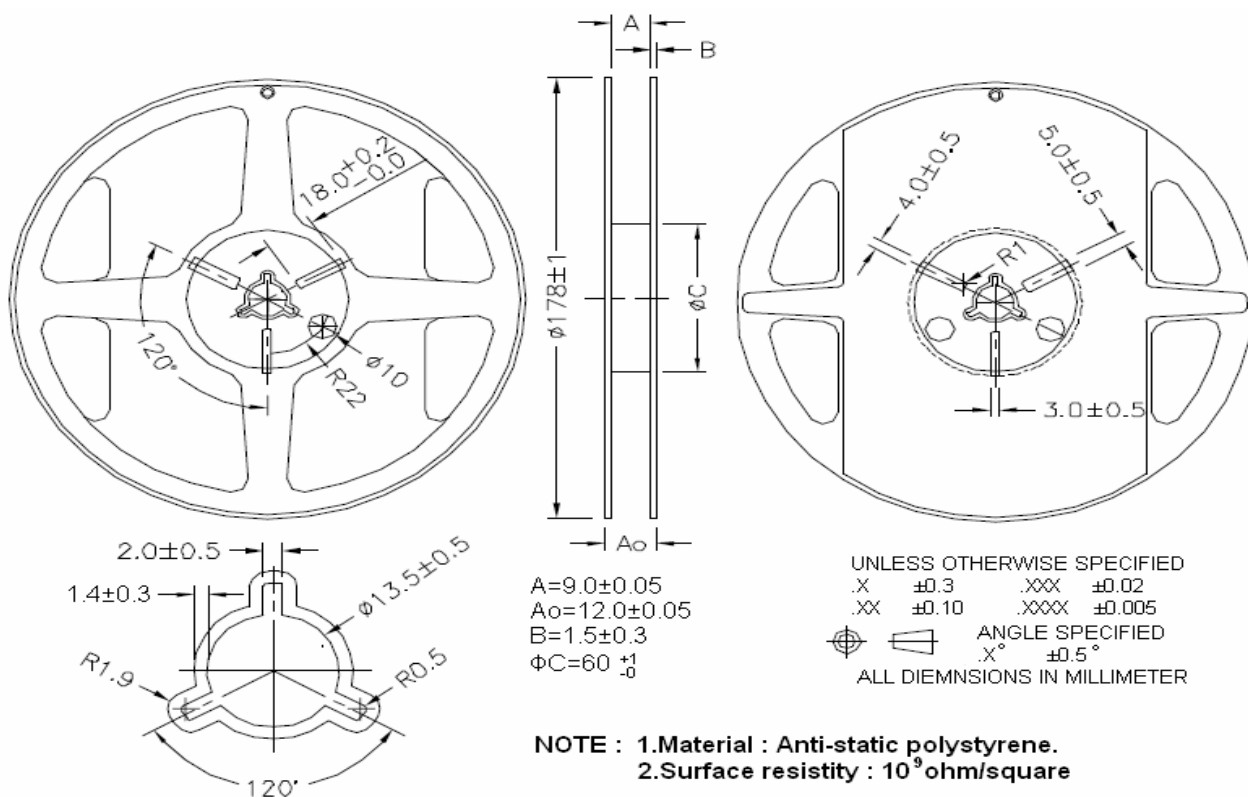
Transient Thermal Response Curves



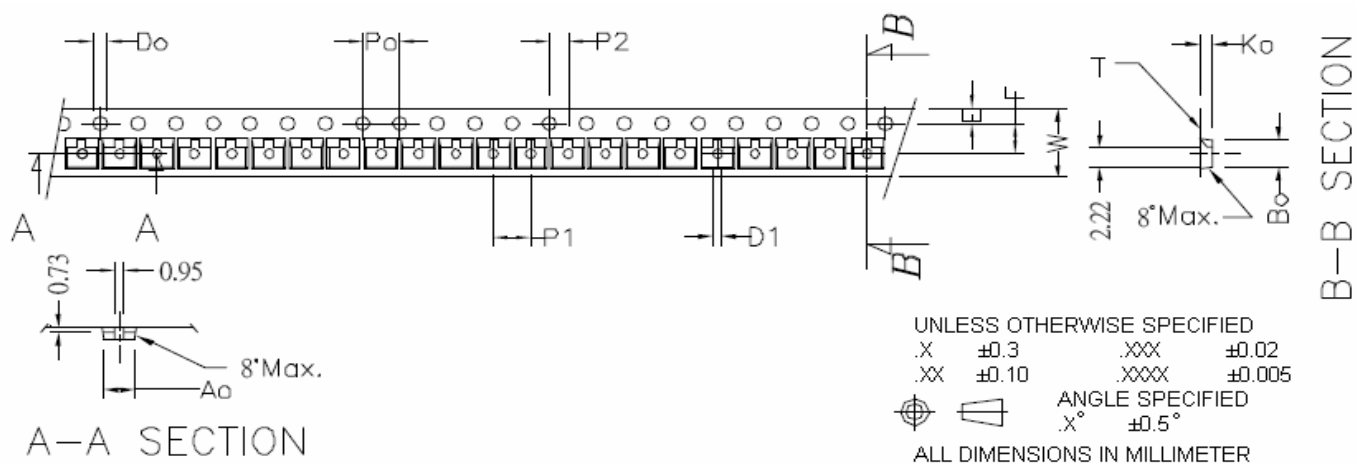
Recommended Soldering Footprint



Reel Dimension

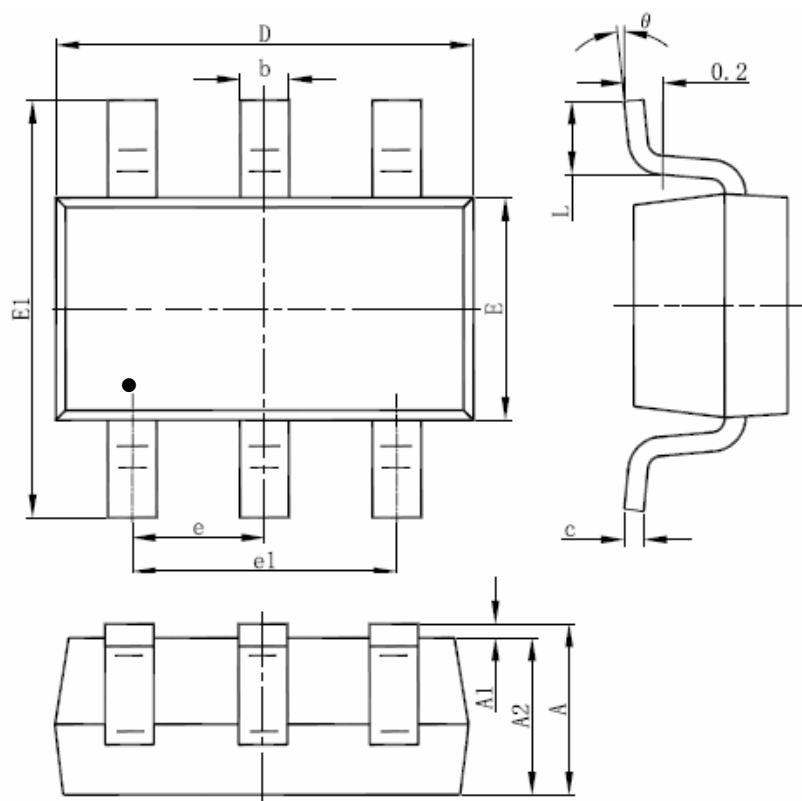


Carrier Tape Dimension

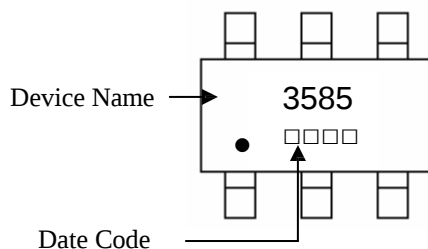


symbol	Ao	Bo	Ko	Po	P1	P2	T
Spec	3.20 ± 0.1	3.00 ± 0.1	1.33 ± 0.1	4.0 ± 0.1	4.0 ± 0.10	2.0 ± 0.05	0.20 ± 0.02
symbol	E	F	Do	D1	W	10Po	
Spec	1.75 ± 0.1	3.5 ± 0.05	1.50 ± 0.10	1.0 ± 0.25	8.0 ± 0.3 -0.1	40.0 ± 0.2	

SOT-26 Dimension



Marking:



6-Lead SOT-26 Plastic
 Surface Mounted Package
 Package Code: N6

Style:

Pin 1. Drain (D)
 Pin 2. Drain (D)
 Pin 3. Gate (G)
 Pin 4. Source (S)
 Pin 5. Drain (D)
 Pin 6. Drain (D)

DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049	E	1.500	1.700	0.059	0.067
A1	0.000	0.100	0.000	0.004	E1	2.650	2.950	0.104	0.116
A2	1.050	1.150	0.041	0.045	e	0.950 (BSC)		0.037 (BSC)	
b	0.300	0.500	0.012	0.020	e1	1.800	2.000	0.071	0.079
c	0.100	0.200	0.004	0.008	L	0.300	0.600	0.012	0.024
D	2.820	3.020	0.111	0.119	θ	0°	8°	0°	8°